ASSOCIATION CONNECTINIELEGTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This clevel	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					rials and N	ials and Mfg Information			
Supplier Inform	ation														
Company name*			Company unique ID			Uı	Unique ID Authority				Respor	Response Date*			
nsemi											2024-0	2024-04-17			
Contact Name			Title - Contact			Pi	Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewa	ards		Product Enviro Compliance			N	NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			Pł	Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewa	ırds	Product Enviro Compliance			N	NA				Produ	Product-Env-Stewards@onsemi.com				
Requeste	equester Item Number Mfr Item		Number		Effe		Version]	Manufacturing Site		Weight*	UOM	Unit Type		
		NCP4060AMNTXG High Voltage Synch		nchronous Buck Conve	erter 2	2024-04-17		PH1			116.91	mg	Each		
	Proccess Information					·									
Terminal Plating / Grid Array Material		ial Te			J-STD-020 MSL Ratir	ng			emperatu	ure Max Time at Peak Tempera		iture Numb	er of Reflow Cyc	eles	
Matte Ti	n (Sn) - annealed	\mathbf{C}	U Alloy		3		260		C	30	seco	nds 3			
omments															
TTENTION: MSI	3 Rated item requires B	ake and Di	ry Pack (after	r electrical test)											
or more informatio	on regarding material con	nposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.22	mg	Supplier	Silicon (Si)	7440-21-3		5.22	mg
Die Attach Solder	6.23	mg	Supplier	Silver (Ag)	7440-22-4		0.1558	mg
			A	Lead (Pb)	7439-92-1	7a	5.7628	mg
			Supplier	Tin (Sn)	7440-31-5		0.3115	mg
Lead Frame	53.15	mg	Supplier	Silver (Ag)	7440-22-4		0.5315	mg
			Supplier	Tin (Sn)	7440-31-5		0.1329	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1169	mg
			Supplier	Chromium (Cr)	7440-47-3		0.1329	mg
			Supplier	Copper (Cu)	7440-50-8		52.2358	mg
Mold Compound-Black	48.02	mg		Epoxy resin	proprietary data		2.2569	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.802	mg
			Supplier	Carbon Black (C)	1333-86-4		0.048	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.6561	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.2569	mg
Plating	2.38	mg	Supplier	Tin (Sn)	7440-31-5		2.38	mg
Wire Bond - Au	1.91	mg	Supplier	Gold (Au)	7440-57-5		1.91	mg